产品描述：

100%全新高品质！

松香助焊剂用于方便焊接。

它可以清洗和防止金属氧化，从而使焊料产生强大的，持久的机械和电气键。

它还可以作为润湿剂，增加焊料流动和焊接工艺的效率。

完美的手机，PC卡等精密电子芯片级助焊剂。

产品规格：

产品：BST-21503A

熔点：60℃

PRODUCT DISPLAY

PRODUCT DETAILS

Name： Soldering Paste
Model： BST-21503A
Size： Φ80*45mm
Weight： 100g
Composition：Solder powder, resin
Melting point:60°C

- ▲ Stable performance,Not volatile, long life cycle, the amount of province;
- ▲ Non-toxic non-irritating odor, the use of safe and reliable;
- ▲ The IC and PCB are not corrosive
- ▲ Its boiling point is only slightly higher than the melting point of solder.

Features: Solder melting at the time of soldering begins to boil endothermic vaporization, which can be maintained at this temperature using IC and PCB temperatures. In the demolition of the chip with a lot of solder paste, it melts fast, you can flow to the BGA chip below. Rosin is solid without solder paste convenient.

PRODUCT PHOTOGRAPH